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Bulletin Date: 6/25/2014	Bulletin Effective Date: 6/25/2014	
Title: EFM32WG Datasheet Revision Notification		
Originator: Ted Batey	Phone: 512-532-5279	Dept: Marketing
Customer Contact: Kathy Haggar	Phone: 512-532-5261	Dept: Sales
Bulletin Details		
Description: Silicon Labs is pleased to announce that version 1.40 of the EFM32WGxxx (Wonder Gecko family) datasheets are now available. The affected datasheets are: EFM32WG230, EFM32WG232, EFM32WG280, EFM32WG290, EFM32WG295, EFM32WG330, EFM32WG332, EFM32WG380, EFM32WG390, EFM32WG395, EFM32WG840, EFM32WG842, EFM32WG880, EFM32WG890, EFM32WG895, EFM32WG940, EFM32WG942, EFM32WG980, EFM32WG990, EFM32WG995. The revision includes a number of key changes to existing min/max/typ values that more accurately reflect the performance of the part. These changes are summarized in Table 1 at the end of this document. In addition, Table 3.12 HFRCO has a new Footnote 3, ensuring frequency bands above 7MHz will always have some overlap across supply voltage and temperature. In addition, new min/max data has been added and other minor updates have been made as follows: <ul style="list-style-type: none">• Removed "preliminary" markings throughout• Updated Current Consumption information• Updated Power Management information• Updated GPIO information• Updated HFXO information• Updated LFRCO information• Updated HFRCO information and figures• Updated ULFRCO information• Added AUXHFRCO chapter• Updated ADC information• Updated DAC information• Updated OPAMP information• Updated ACMP information• Updated VCMP information• Added EBI chapter See Table 1 at the end of this document for additional details.		
Reason: Updated specifications based on the results of additional silicon characterization. There are no changes to the devices delivered to the customer.		
Product Identification: The following orderable part numbers are affected: EFM32WG230F64-QFN64 EFM32WG230F128-QFN64		

EFM32WG230F256-QFN64
EFM32WG232F64-QFP64
EFM32WG232F128-QFP64
EFM32WG232F256-QFP64
EFM32WG280F64-QFP100
EFM32WG280F128-QFP100
EFM32WG280F256-QFP100
EFM32WG290F64-BGA112
EFM32WG290F128-BGA112
EFM32WG290F256-BGA112
EFM32WG295F64-BGA120
EFM32WG295F128-BGA120
EFM32WG295F256-BGA120
EFM32WG330F64-QFN64
EFM32WG330F128-QFN64
EFM32WG330F256-QFN64
EFM32WG332F64-QFP64
EFM32WG332F128-QFP64
EFM32WG332F256-QFP64
EFM32WG380F64-QFP100
EFM32WG380F128-QFP100
EFM32WG380F256-QFP100
EFM32WG390F64-BGA112
EFM32WG390F128-BGA112
EFM32WG390F256-BGA112
EFM32WG395F64-BGA120
EFM32WG395F128-BGA120
EFM32WG395F256-BGA120
EFM32WG840F64-QFN64
EFM32WG840F128-QFN64
EFM32WG840F256-QFN64
EFM32WG842F64-QFP64
EFM32WG842F128-QFP64
EFM32WG842F256-QFP64
EFM32WG880F64-QFP100
EFM32WG880F128-QFP100
EFM32WG880F256-QFP100
EFM32WG890F64-BGA112
EFM32WG890F128-BGA112
EFM32WG890F256-BGA112
EFM32WG895F64-BGA120
EFM32WG895F128-BGA120
EFM32WG895F256-BGA120
EFM32WG940F64-QFN64
EFM32WG940F128-QFN64
EFM32WG940F256-QFN64
EFM32WG942F64-QFP64
EFM32WG942F128-QFP64
EFM32WG942F256-QFP64
EFM32WG980F64-QFP100
EFM32WG980F128-QFP100
EFM32WG980F256-QFP100
EFM32WG990F64-BGA112
EFM32WG990F128-BGA112
EFM32WG990F256-BGA112
EFM32WG995F64-BGA120



Bulletin #1406251

EFM32WG995F128-BGA120
EFM32WG995F256-BGA120

This change is considered a minor change which does not affect form, fit, function, quality, or reliability. The information is being provided as a customer courtesy.

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Customer Actions Needed:
None.

Table 1: EFM32WGxx Datasheet Rev 1.40 - Summary of Key Changes

Table*	Symbol	Parameter	Condition	Datasheet Rev 1.31			Datasheet Rev 1.40			Unit
				Min	Typ	Max	Min	Typ	Max	
3.2 General Operating Conditions	V _{DDOP}	Operating Supply Voltage		1.85		3.8	1.98		3.8	V
3.4 Current Consumption	I _{EM0}	EM0 Current T _{AMB} = 25 °C	48 MHz	224.8			225	236	μA/MHz	
			28 MHz	226.1			226	238	μA/MHz	
			21 MHz	228.0			228	240	μA/MHz	
			14 MHz	230.4			230	243	μA/MHz	
			11 MHz	232.3			232	245	μA/MHz	
			6.6 MHz	237.5			238	250	μA/MHz	
			1.2 MHz	270.6			271	286	μA/MHz	
	I _{EM1}	EM1 Current T _{AMB} = 25 °C	48 MHz	63.3			63	75	μA/MHz	
			28 MHz	63.6			64	75	μA/MHz	
			21 MHz	64.7			65	76	μA/MHz	
	I _{EM2}	EM2 Current T _{AMB} = 25 °C	14 MHz	66.7			67	79	μA/MHz	
			11 MHz	68.4			68	81	μA/MHz	
			6.6 MHz	73.7			74	87	μA/MHz	
			1.2 MHz	106.0			106	120	μA/MHz	
3.6 Power Management	I _{BOD}	BOD threshold, falling external supply	T _{AMB} = 25 °C	0.95			0.95	1.7	μA	
			T _{AMB} = 85 °C	3.0			3.0	4.0	μA	
	I _{EM3}	EM3 Current	T _{AMB} = 25 °C	0.65			0.65	1.3	μA	
	I _{EM4}	EM4 Current	T _{AMB} = 25 °C	2.65			2.65	4.0	μA	
	V _{BODextthr+}	BOD threshold, rising external supply	T _{AMB} = 85 °C	0.02			0.02	0.055	μA	
			T _{AMB} = 25 °C	0.44			0.44	0.9	μA	
3.7 Flash	V _{FLASH}	Flash erase/write supply voltage		1.8		3.8	1.98		3.8	V
3.8 GPIO	V _{IOOH}	Output high voltage	Sourcing 6 mA, V _{DD} = 1.98V	0.75V _{DD}			0.75V _{DD}			V
			Sourcing 6 mA, V _{DD} = 3.0V	0.95V _{DD}			0.85V _{DD}			V
			Sourcing 20 mA, V _{DD} = 1.98V	0.7V _{DD}			0.6V _{DD}			V
			Sourcing 20 mA, V _{DD} = 3.0V	0.9V _{DD}			0.8V _{DD}			V
	V _{IOOL}	Output low voltage	Sinking 6 mA, V _{DD} = 1.98V		0.25V _{DD}			0.3V _{DD}		V
			Sinking 6 mA, V _{DD} = 3.0V		0.05V _{DD}			0.2V _{DD}		V
			Sinking 20 mA, V _{DD} = 1.98V		0.3V _{DD}			0.35V _{DD}		V
			Sinking 20 mA, V _{DD} = 3.0V		0.1V _{DD}			0.25V _{DD}		V
3.11 LFRCO	I _{LFRCO}	Input leakage current			±25		±0.1	±100	nA	
3.12 HFRCO	I _{HFRCO}	Current consumption			190		300		nA	
3.13 ULFRCO	f _{ULFRCO}	Oscillation frequency	28 MHz	106			165	215	μA	
			21 MHz	93			134	175	μA	
			14 MHz	77			106	140	μA	
			11 MHz	72			94	125	μA	
			6.6 MHz	63			77	105	μA	
			1.2 MHz	22			25	40	μA	
3.15 DAC	I _{DAC}	Active current	1 ksps, 12 bit NORMAL	38			17		μA	
3.16 OPAMP	I _{OPAMP}	Active current	BIASPROG=0xF, HALFBIAS=0x0	400			370	460	μA	
			BIASPROG=0x7, HALFBIAS=0x1	100			95	135	μA	
			BIASPROG=0x0, HALFBIAS=0x1	13			13	25	μA	
3.17 ACMP	V _{ACMPOFFSET}	Input offset voltage	Unity Gain, V _{SS} <V _{In} <V _{DD} , OPAXHCMDIS=0	6		-13	0	11	mV	
3.18 VCMP	I _{VCMP}	Active current	Offset voltage	10		-12	0	12	mV	
			BIASPROG=0b0000, HALFBIAS=1	0.1		0.3	0.6	μA		
			BIASPROG=0b1111, HALFBIAS=0	14.7		22	35	μA		
3.19 LCD	V _{BOOST}	VCMP hysteresis		17			61	210	mV	
			LEVEL0	3.0			3.02		V	
			LEVEL1	3.08			3.15		V	
			LEVEL2	3.17			3.28		V	
			LEVEL3	3.26			3.41		V	
			LEVEL4	3.34			3.54		V	
			LEVEL5	3.43			3.67		V	
			LEVEL6	3.52			3.73		V	
3.27 Digital Peripherals	I _{DIGITAL}	Boost voltage	LEVEL7	3.6			3.74		V	
			USART current	7.5			4.0		μA/MHz	
			UART current	5.63			3.8		μA/MHz	
			LEUART current	150			194		nA	
			I _{I2C}	6.25			7.6		μA/MHz	
			I _{TIMER}	8.75			6.5		μA/MHz	
			I _{LETIMER}	150			85.8		nA	
	I _{PCNT}	PCNT current		100			91.4		nA	
	I _{RTC}	RTC current		100			54.6		nA	
	I _{LCD}	LCD current		100			72.7		nA	
	I _{AES}	AES current		2.5			1.8		μA/MHz	
	I _{GPIO}	GPIO current		5.31			3.4		μA/MHz	
	I _{EBC}	EBC current		1.56			6.5		μA/MHz	
	I _{PRS}	PRS current		2.81			3.9		μA/MHz	
	I _{DMA}	DMA current		8.12			10.9		μA/MHz	

* Note: Table numbers may vary by datasheet. Numbers listed refer to EFM32WG995.